1. HS4 & HS5 Placement Instructions:
   a. Cut the Heat Sink into two equal vertical halves.
   b. Trim the Mounting lead to fit in the PCB Mounting Hole.
2. For all jumpers (JP1 to JP8) use thin insulated wire to mount across the nodes.

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: DD1
COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

<table>
<thead>
<tr>
<th>PCB VIEWED FROM BOTTOM SIDE</th>
<th>BOARD #: TIDA-01557</th>
<th>REV: E1</th>
<th>SVN REV: Not In VersionControl</th>
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<tbody>
<tr>
<td>LAYER NAME = M6 Assembly Bottom</td>
<td>TID #: TIDA-01557</td>
<td></td>
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<tr>
<td>PLOT NAME = Bottom Assembly Drawing</td>
<td>GENERATED: 12/15/2017 2:40:09 PM</td>
<td>TEXAS INSTRUMENTS</td>
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